

Form Type	Distribute	Version	ersion 2.0		Ref		IPC 175	2A	Sectionals		Manufacturi Info/ Materia Info		Subsectionals	s D, A
					S	upplier lı	nformatio	on						
Company Name	TE Connectiv	Request Document	ID			Contact	Name	Penica	a, John R	Conf	tact Title	Μç	gr Environmental	Engineering
Company Unique ID	TE Connectivi	ity Response	Date	2014-12-2	3	Contact	Email	jrpenio	a@te.com					
Contact Phone	Number	+1-717-592	-3266											
	i					Legal St	tatement							
Supplier Acceptance	true													
Legal Statemen	t													
The information j	provided in this	document is base	d upo	n reasonab	le inqui	ry of our s	suppliers.	This inf	formation is	subje	ct to change.	. Thi	is information doe	es not in any
way modify exist	ing purchase sp	ecifications or ex	isting	contractual	or otne			s betwe	en le Conr	iectivi	ty (or its amili	atec	d companies) and	its customers.
Manufacturer Item number	1825516-2	Amount		3685.0		Version	duct	-		Iden	tity			
Manufacturer Item Name		Weight Uo	Weight Uom		mg		Mfr Site		Authority		ority			
Date		UOM		Each		I		1		1		<u> </u>		
EURoHS-0508	Product(s) me	ets EU RoHS re	guiren		olication	of the se	elected ev	emption	n(s) - true					
ChinaRoHS-	` '		•					-	. ,	ith an	Environment	al P	Protection Use Pe	riod under
0508	China's Meas	ures for Administ	ration	of the conti	ol of po	llution by	Electroni	c Inform	nation Produ	ucts -	true			
EUREACH-1213	Product(s) do Reviewed	es not contain RI	ACH	Substances	of Ver	ry High Co	oncern ab	ove the	limits per t	he de	finition within	RE	ACH - Not Availa	ble / Not
					Man	ufacturin	g Inform	ation			_		<u> </u>	•
J-STD-020 MSL		Max Total a				Ramp R	ate			Wav				
Rating Classification		Wave Time Max Wave		0.0		D					itional Info			
Temp		Solder Tim	Solder Time		0.0		Ramp Down Rate			Psl Rating Reflow				
Max Time Within 5		Psl Rating Wave					Package Designator		Size			0.0		
Time Above 217	7	Reflow Additional	Reflow Additional Info				Preheat Max Temp		Alloy		ninal Base /	NAC		
Preheat Duration		bulk Solder Termination		NAC		Nbr or Reflow Cycles			Termin Plating			NAC		
Preheat Min		Nbr of		0		Compor				Shap	oe	NAC		
Temp		Instances				Temp S Product D								
Sub- Item/Material/ Substance	Level	Name		stance gory	Substa		Substar	Substance Concentration		Quantity		Jnit UOM		Exemption
Material	1	Contact Spring-Steel							1.0		40.0		mg	
Substance	2	Manganese	Supr	olier	7439-9	96-5	0.75		1.0		0.3		mg	
	2	Silicon	Supp		7440-2		0.22		1.0		0.088		mg	
Substance	2	Carbon	Supp	olier	7440-4	4-0	0.75		1.0		0.3		mg	
Substance	2	Iron	Supp	olier	7439-89-6		98.28		1.0		39.312		mg	
Material	1	Spring-Steel							1.0		40.0		mg	
	2	Silicon	Supp	plier 7440-2		21-3	0.22		1.0		0.088		mg	
	2	Manganese	Supp	olier 7439-9					1.0		0.18		mg	
	2	Carbon	Supp			14-0	0.75		1.0		0.3		mg	
	2	Iron	Supp	plier 7439		89-6	98.58		1.0		39.432		mg	
Material	1	Movable Contact Silver Plated-Silver							1.0		0.3		mg	
Substance	2	Silver	Supp	plier 7440		22-4 100.0			1.0		0.3	mg		
	1	Lock Washer- Steel							1.0		140.0		mg	
Substance	2	Manganese	Supp	olier 7439-9		96-5	0.3		1.0		0.42		mg	
	2	Carbon	Supp						1.0		1.19		mg	
	2	Silicon	Supp						1.0		0.308		mg	
Substance	2	Iron	Supp		7439-8		98.63		1.0		138.082		mg	
Material	1	Hex Nut- Copper Alloy							1.0		272.76		mg	
Substance	2	Zinc	Supp	olier	7440-6	66-6	37.3		1.0		101.73948		mg	
Substance	2	Copper	Supp	olier	7440-5	60-8	59.0		1.0		160.9284		mg	

Substance	2	Lead	Lead/Lead Compounds	7439-92-1	3.7	1.0	10.09212	mg	6(c) Lead as an alloying element in copper containing up to 4% lead by weight
Material	1	Insulating plate				1.0	50.0	mg	
Substance	2	Phenol	Supplier	108-95-2	100.0	1.0	50.0	mg	
Material	1	Case-Phenol				1.0	750.0	mg	
Substance	2	Phenol	Supplier	108-95-2	100.0	1.0	750.0	mg	
Material	1	Fixed Contact- Copper				1.0	576.8	mg	
Substance	2	Copper	Supplier	7440-50-8	100.0	1.0	576.8	mg	
Material	1	Sleeve Nickel Plated-Nickel				1.0	17.0	mg	
Substance	2	Nickel	Nickel	7440-02-0	100.0	1.0	17.0	mg	
Material	1	Hex Nut Nickel Plated-Nickel				1.0	2.24	mg	
Substance	2	Nickel	Nickel	7440-02-0	100.0	1.0	2.24	mg	
Material	1	Movable contact-Copper				1.0	59.7	mg	
Substance	2	Copper	Supplier	7440-50-8	100.0	1.0	59.7	mg	
Material	1	Fixed Contact- Silver				1.0	3.2	mg	
Substance	2	Silver	Supplier	7440-22-4	100.0	1.0	3.2	mg	
Material	1	Plunger-PC				1.0	190.0	mg	
Substance	2	Carbonic dichloride, polymer with 4,4-(1- methylethylide ne)bis[phenol], 4-(1,1- dimethylethyl)p henyl ester	Supplier	103598-77-2	100.0	1.0	190.0	mg	
Material	1	Sleeve-Copper Alloy				1.0	1543.0	mg	
Substance	2	Copper	Supplier	7440-50-8	59.0	1.0	910.37	mg	
Substance	2	Zinc	Supplier	7440-66-6	37.3	1.0	575.539	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	3.7	1.0	57.091	mg	6(c) Lead as an alloying element in copper containing up to 4% lead by weight